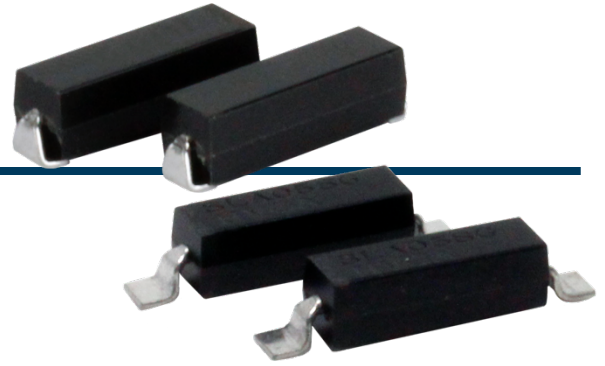




SLA-M SERIES

5 to 25kV, 150 to 650mA, 100nS
Surface Mount Diodes



Features

- Long Surface Mount Package
- J Lead or Gullwing Package Option
- Available in Cut Tape and 1000 Piece Reels
- Molded Plastic Body, ANSI/UL94 V-0 Rated Material

Specifications¹

Part Number	V _{RRM} V	I _{FAVM1} ² mA	I _{FAVM2} ² mA	I _{FAVM3} ² mA	V _F V	I _R μA	I _{FSM} A	C _J pF	T _{RR} nS	R _{θJL} °C/W	R _{θJC} °C/W
J Lead Subseries (Figure 1)											
SLA05M	5000	650	330	300	12	2	15	6.5	100	16	30
SLA06M	6000	575	300	270	13	2	15	5.0	100	16	30
SLA08M	8000	550	280	250	16	2	15	4.5	100	16	30
SLA10M	10000	500	250	230	20	2	15	3.5	100	16	30
SLA12M	12000	475	200	190	24	2	15	2.7	100	16	30
SLA15M	15000	250	85	100	27	2	15	2.1	100	16	30
SLA20M	20000	200	70	85	35	2	15	1.8	100	16	30
SLA25M	25000	150	60	75	40	2	15	1.5	100	16	30
Gullwing Subseries (Figure 2)											
SLA05MG	5000	650	330	300	12	2	15	6.5	100	16	30
SLA06MG	6000	575	300	270	13	2	15	5.0	100	16	30
SLA08MG	8000	550	280	250	16	2	15	4.5	100	16	30
SLA10MG	10000	500	250	230	20	2	15	3.5	100	16	30
SLA12MG	12000	475	200	190	24	2	15	2.7	100	16	30
SLA15MG	15000	250	85	100	27	2	15	2.1	100	16	30
SLA20MG	20000	200	70	85	35	2	15	1.8	100	16	30
SLA25MG	25000	150	60	75	40	2	15	1.5	100	16	30

Temperature °C	
Storage Temperature	-55 to 175
Operating Temperature	-55 to 150 (SLA05M to SLA12M, SLA05MG to SLA12MG) -55 to 125 (SLA15M to SLA25M, SLA15MG to SLA25MG)
Maximum Junction Temperature	150 (SLA05M to SLA12M, SLA05MG to SLA12MG) 125 (SLA15M to SLA25M, SLA15MG to SLA25MG)

¹25°C ambient temperature unless stated otherwise.

²Check Specification Definitions for conditions details.



Drawings

Dimensions in inches [mm], tolerances ± 0.020 except as noted

Figure 1 – J Lead Subseries

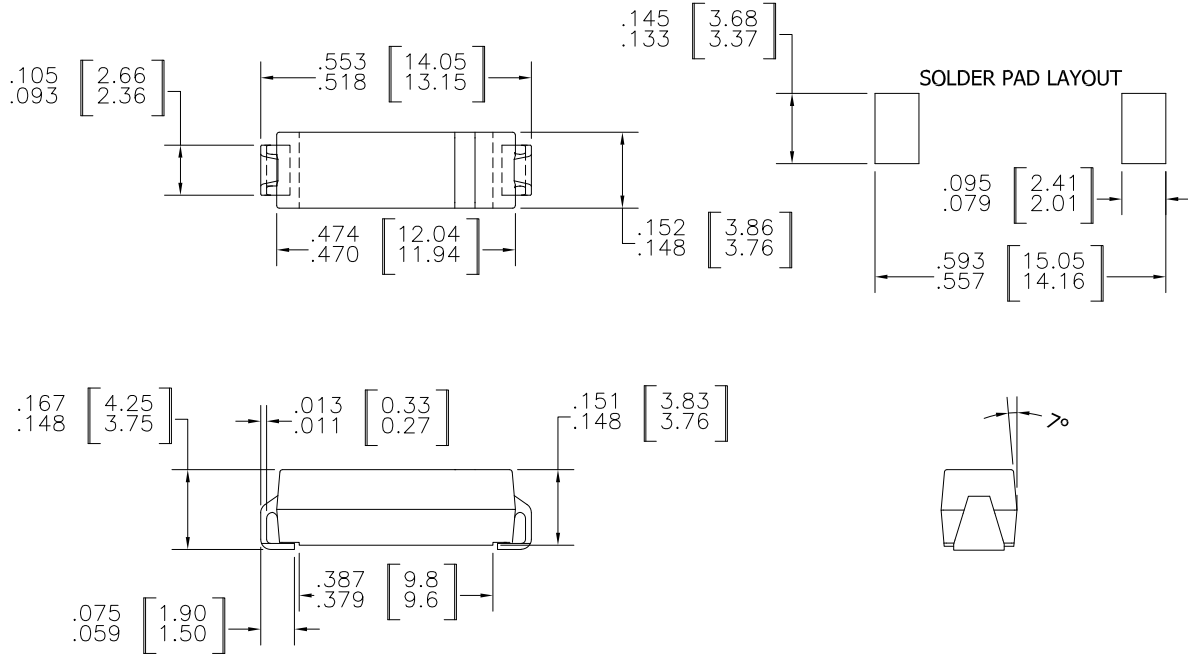
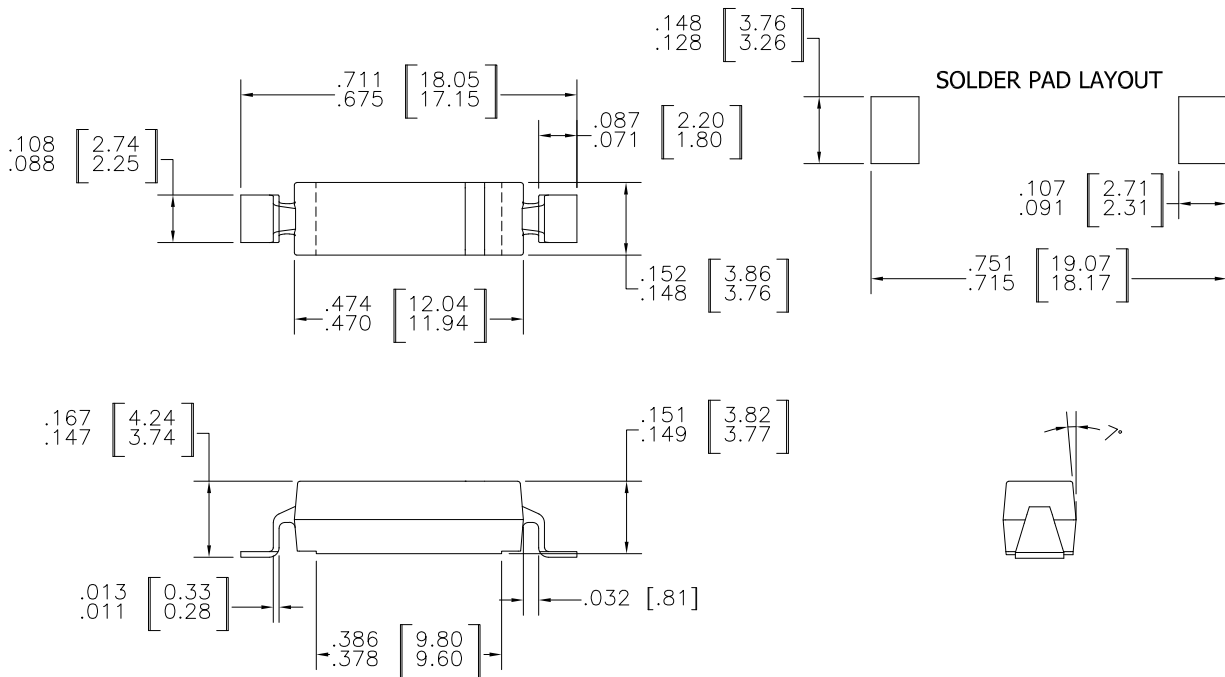
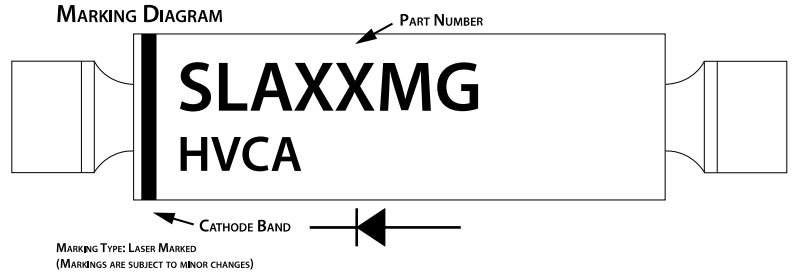
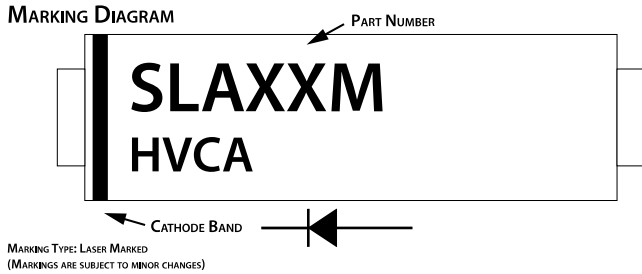
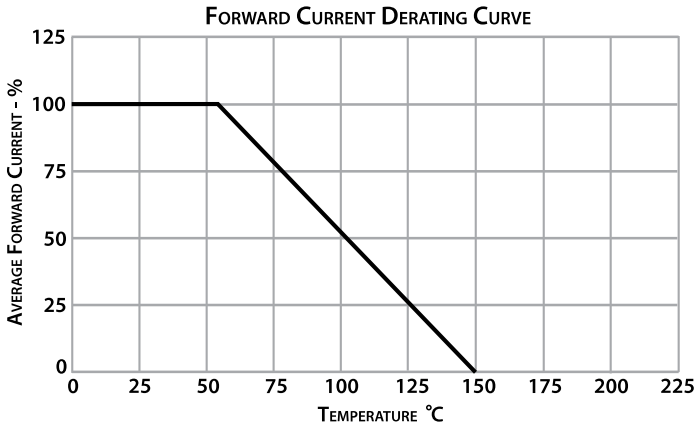


Figure 2 – Gullwing Subseries

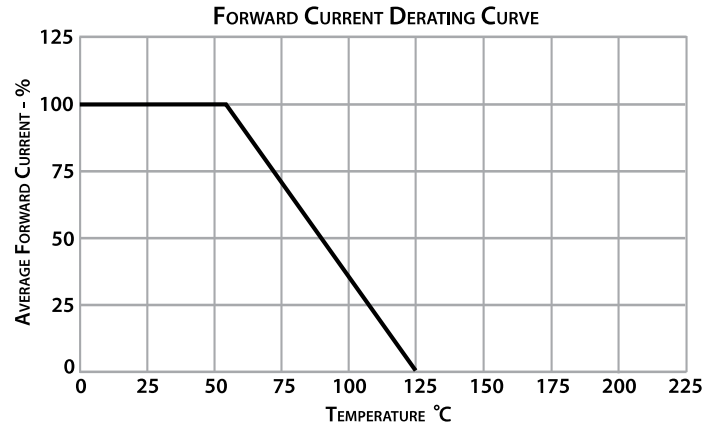




SLA05M to SLA12M, SLA05MG to SLA12MG



SLA15M to SLA25M, SLA15MG to SLA25MG



Specification Definitions

Specifications		Conditions
V_{RRM}	Maximum Repetitive Reverse Voltage	-
I_{FAVM1}	Maximum Average Forward Current	At T _L = 55°C
I_{FAVM2}	Maximum Average Forward Current	At T _L = 100°C
I_{FAVM3}	Maximum Average Forward Current	At T _C = 70°C
V_F	Maximum Forward Voltage Drop	At I _{FAVM1}
I_R	Maximum Leakage Current	At V _{RRM}
I_{FSM}	Maximum Surge Current	At 8.3 mS, Single Half Sine
C_J	Typical Junction Capacitance	At V _R = 0VDC, f = 1MHz
T_{RR}	Maximum Reverse Recovery Time	I _F = 0.5 I _{FAVM1} ; I _R = -I _{FAVM1} ; I _{RR} = -0.25 I _{FAVM1}
R_{θJL}	Typical Thermal Resistance Junction to Lead	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads
R_{θJC}	Typical Thermal Resistance Junction to Case	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads



Note: Specifications subject to change without notice. Photo is representation only.